



Supplemental Application Data Sheet

Application Information

Application Number::	<u>10/618,985</u>
Filing Date::	<u>07/14/03</u>
Application Type::	Regular
Subject Matter::	Utility
Title::	THERMOPLASTIC MOLDING PROCESS
Attorney Docket Number::	JETTA-003US
Request for Early Publication?::	No
Request for Non-Publication?::	No
Total Drawing Sheets::	2
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority type::	Inventor
Primary Citizenship Country::	CN
Status::	Full Capacity
Given Name::	Tit
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Family Name::	WONG
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Country of Residence::	CN

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Representative Information

Representative Customer Number::	28156	
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Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Non- Provisional of	60/409,217	09/09/02

Assignment Information

Assignee name:: J.T. LABS, LTD.

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